

Prof. Kotaro INOUE
Dean, School of Materials and Chemical Technology

Prof. Hidetoshi SEKIGUCHI
Dean, School of Engineering

Prof. Jun-ichi TAKADA
Dean, School of Environmental and Society

Call for 2023 Fall Applications

International Exchange Program (Outbound) of the Engineering Schools

We are pleased to announce that a call for Fall, the **International Exchange Program (Outbound) of the Engineering Schools, is now open**. Students who wish to apply for this exchange program must submit the below documents to the International Exchange Team of the Engineering Schools.

Before applying, students must read through [the website](#) and comply with the guidelines.

When the following situations (a)-(d) will continue, or not improve by 2-3 months before the start of your study abroad, you may discontinue your overseas study or change your plan.

- (a) The country or area restricts or refuses entry to Japanese travelers and those arriving from Japan, or imposes restrictions following entry.
(Japanese language only) https://www.anzen.mofa.go.jp/covid19/pdfhistory_world.html
- (b) Tokyo Tech considers it dangerous.
<https://www.titech.ac.jp/english/enrolled/health/coronavirus.html>
- (c) When the area in which you (plan to) stay is raised to Level 2 or higher.
- (d) Your host university refuses admittance to the school
You must follow the instructions of your host supervisor or coordinators from the partner university.

◆ **Program Categories Open for Application: C1 (RWTH, University of the Basque Country) and C2 ~ C4.**

Start studying abroad: September, October and November 2023

*The period of stay shall not be less than 60 days.

◆ **Prospective Applicants: Students who are enrolled in a master's or doctoral degree program at the Engineering Schools (School of Engineering, School of Materials and Chemical Technology, and School of Environment and Society) as of April 1, 2023.**

- Working adult students are **NOT** eligible.
- Doctoral students who wish to study abroad to fulfill the requirements for Tokyo Tech projects and to earn credits for off-campus are not eligible.
- Undergraduate 4th students who have passed the exam for a master's degree program at the Engineering Schools starting in April 2023 are also eligible.
- Students who graduate early in 3.5 years will be allowed to apply for the Fall Dispatch if they are approved by the rules set by each school and department.

◆ **Deadline: Noon on Wednesday, May 30, 2023**

- Applications that arrive after this deadline will not be processed, regardless of reason.

◆ **Interview: Afternoon on Wednesday, June 14, 2023**

- Details regarding location and time for the interview will be notified by email after the submission of the application documents. Depending on the infection status of COVID-19, we will ask the candidates for the interview on Zoom.
- If an applicant is unable to attend the interview for legitimate reasons, Request the Time of the Interview [Form 3] must be submitted with the other application documents to request the interview to be scheduled for a different time. The applicant may not request to reschedule the interview after the submission of the application under any circumstances.
- In principle no special measures shall be taken for reasons such as suspension due to infectious diseases (e.g. COVID-19, the flu, etc.) or external factors (e.g. traffic delays), so please apply with time to spare and under the thorough management of your physical condition.

◆ **Application Documents:**

- ✓ Incomplete applications and applications received after the deadline will not be accepted under any circumstances.
- ✓ Submitted documents will not be returned.

Application Documents	Saving Format
1) Application form: [Form 1-A] (Please use the latest version)	PDF
2) Application form: [Form 1-B] (Please use the sheet of “applist2_English”)	Excel
3) Resume in English *Free format (Click here for sample resume)	PDF
4) A copy of your English language test scores (TOEFL® or TOEIC® score report) <ul style="list-style-type: none"> • Some universities may have their own English language requirements, such as TOEFL iBT® or IELTS scores. The applicant must check with the university in which you wish to enroll. • Applicants may submit a new, better score report to the interviewers in person during the interview. 	PDF
5) Academic Transcript in English (and Japanese if any) <ul style="list-style-type: none"> • The transcript must include your academic record of the previous year. Students in their first year of a master’s degree program must attach their undergraduate final grade academic transcripts. 	PDF
6) Recommendation Letter [Form 2] written by Academic Supervisor (Please use the latest version)	PDF
7) Statement of Reason for those below. *Free format <ul style="list-style-type: none"> • C3-b applicants who cannot apply for or was rejected by the university-wide program conducted by International Student Exchange Division (written by applicants) • All C4 applicants (written by applicants, and by their Chair of Department, Head of Graduate Studies or academic supervisor) 	PDF
8) A copy of the email that shows the applicant get acceptance consent from a host professor <ul style="list-style-type: none"> • All C3 and C4 applicants • Some C2 applicants who already have the consent above for any reason 	PDF

◆ **How to Submit the Application Documents: By email saving onto [T2BOX](#).**

Methods of submitting documents are shown below.

- 1) Subject Line: Eng. Schools Outbound Program_Application_(Name)_(Student No.)
- 2) Mail Text must include:
 - 2)-1 The URL of the page to your T2Box
 - 2)-2 The password of your T2Box
 - 2)-3 Expiration date of your T2Box
- 3) Each document must be saved in a prescribed format as above.
- 4) Each document must NOT be set with a password for each, but set a password for T2BOX.

◆ **Where to Submit or Inquire:**

International Cooperation Office, Engineering Schools
Main Bldg., Floor 2, Rm 256 [Mailbox: H-106]

☎ 3859 ✉ ko.intl@jim.titech.ac.jp

◆ **Application Guidelines:**

<p>Program Outline</p>	<p>The Engineering Schools offer an international exchange program that consists of five categories, (C1), (C2), (C3), (C4), and (C5). Study abroad expenses are partially provided to successfully nominated students.</p> <p>Based on the Engineering Schools' funding policy for its international exchange program, financial support is provided for</p> <ol style="list-style-type: none"> 1) Outbound students who will participate in research under the supervision of professors in the host university 2) Outbound students who will conduct research to broaden their own research field <p>Students engaging in the following are NOT eligible to receive funding through this program.</p> <ol style="list-style-type: none"> 1) Joint research between an overseas university and Tokyo Tech 2) Research related to students' thesis research or doctoral dissertation 3) Study abroad solely focusing on acquiring course credits 4)
<p>Call for Applications</p>	<p>Announcements will be made on the Tokyo Tech website and also will be sent to each faculty who belongs to the Engineering Schools.</p>
<p>Eligibility</p>	<ol style="list-style-type: none"> 1) Students on leave of absence are NOT eligible. 2) Applicants planning to study in their home country are NOT eligible. 3) Only students with a GPA of 2.3 (Maximum 3.0) or higher in the previous year are eligible to apply. 4) Consideration will be given to students who actively participate in international activities or classes held by the Engineering Schools or Tokyo Tech. Please mention this in the application form if you have such experiences.
<p>Language Proficiency Requirements</p>	<p>Applicants must satisfy the following English proficiency requirements: <i>TOEFL iBT</i>[®] score of 70 or higher and/or TOEIC score of 650 or higher. However, even if their score is below this level, students may apply for the program if they have special reasons (e.g., have proficiency in language used in the country where the host university is located, have good English conversation ability that is not reflected in the scores). In such cases, students must attach a statement (free format) explaining these skills to their application.</p>
<p>Screening Method</p>	<p>Face to face interview in English</p> <ul style="list-style-type: none"> • An applicant will be interviewed by multiple faculty members for 10 minutes (The first 5 minutes is for self-introduction, motivation, and research plan presentation, the latter 5 minutes is for questions and answers) • An applicant is not allowed to read scripts or use a PC and/or projector <p>[Note] If the number of applicants is large, only those selected by the initial screening (examination of application documents) will be interviewed.</p>
<p>Financial Support for Outbound Students</p>	<ul style="list-style-type: none"> • Round trip travel expense and/or scholarship is provided. • Application fees and expenses for visa acquisition are NOT provided. • In the case of Japanese government (MEXT) scholarship students, only the round-trip travel expense (airfare) is provided. Also, please note that there might be a possibility for those who participate in this program to lose their eligibility to receive the MEXT scholarship not only during the stay abroad but also after coming back to Tokyo Tech. Please confirm the detailed and latest information about this with Student Support Division. gak.sei@jim.titech.ac.jp • If other scholarships or financial aids are provided to students by Tokyo Tech, the amount of the financial support under this program will be adjusted.
<p>Important Points to Note</p>	<ul style="list-style-type: none"> • Applicants must carefully determine their period of study abroad, taking into consideration the academic calendars of Tokyo Tech and the university in which they wish to enroll. The International Cooperation Office of the Engineering Schools will NOT coordinate schedules of students with classes or courses at Tokyo Tech. It is the applicant's responsibility to manage his/her own schedule. • Applicants for (C2) should note that some universities require applications to be completed approximately 3 months prior to enrollment. • Students must be a "Ryugaku (Study-Abroad)" status but "Kyugaku (Leave of Absence)" at Tokyo Tech while studying abroad through this program regardless of the category and duration.

◆ **Grade Requirements:**

Students applying for categories (C1), (C2), (C3), and (C4) must state their GPA for the previous academic year in their application form. GPA must be calculated based on the calculation method below and applicants must have a GPA of 2.3 or higher.

How to calculate your Grade Point Average according to the JASSO evaluation scale						
Grade Conversion Table						
	Grade					
Four-level grading scale (Type 1)	—	Excellent	Good	Fair	Fail	
Four-level grading scale (Type 2)	—	A	B	C	F	
Four-level grading scale (Type 3)	—	100–80	79–70	69–60	59 or lower	
Five-level grading scale (Type 4)	100–90	89–80	79–70	69–60	59 or lower	
Five-level grading scale (Type 5)	S	A	B	C	F	
Five-level grading scale (Type 6)	A	B	C	D	F	
Grade Evaluation Point (GEP)	3	3	2	1	0	

$$\frac{(\text{Number of Credit for GEP3} \times 3) + (\text{Number of Credit for GEP2} \times 2) + (\text{Number of Credit for GEP1} \times 1) + (\text{Number of Credit for GEP0} \times 0)}{\text{Total Number of Credits}}$$

First, refer to the above table to convert your grades to Grade Evaluation Points (GEP) and calculate the following.

- I The number of credits with a GEP of 3 multiplied by three
- II The number of credits with a GEP of 2 multiplied by two
- III The number of credits with a GEP of 1 multiplied by one
- IV The number of credits with a GEP of 0 multiplied by zero

To calculate your GPA, divide the sum of I, II, III, and IV by the number of total credits earned.

◆ **For supplements, please check [Tokyo Tech HP](#) or [Program HP](#).**

- The Engineering Schools' partner universities show their own requirements.
- Please carefully read our FAQs before contacting us.

* New requirements might be added. Please check out the latest information accordingly on the web and contact ko.intl@jim.titech.ac.jp before you submit the applications.